

TIDA-01585 REV E1 Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPCB	1		TIDA-01585	Any	Printed Circuit Board	
C1	1	47uF	EEE-FK1H470XP	Panasonic	CAP, AL, 47 µF, 50 V, +/- 20%, 0.68 ohm, AEC-Q200 Grade 2, SMD	SMT Radial D8
C2, C9, C10	3	1000pF	06035A102KAT2A	AVX	CAP, CERM, 1000 pF, 50 V,+/- 10%, C0G/NP0, 0603	0603
C3, C7, C8	3	1uF	06033C105KAT2A	AVX	CAP, CERM, 1 µF, 25 V,+/- 10%, X7R, 0603	0603
C4	1	0.1uF	06035C104KAT2A	AVX	CAP, CERM, 0.1 µF, 50 V,+/- 10%, X7R, 0603	0603
C5	1	10uF	C3216X5R1H106K160AB	TDK	CAP, CERM, 10 µF, 50 V,+/- 10%, X5R, 1206	1206
C6	1	0.01uF	C1608NP01H103J080AA	TDK	CAP, CERM, 0.01 µF, 50 V,+/- 5%, C0G/NP0, 0603	0603
C13	1	10uF	C2012X7R1A106M125AC	TDK	CAP, CERM, 10 µF, 10 V,+/- 20%, X7R, 0805	0805
J1	1		ED555/4DS	On-Shore Technology	Terminal Block, 3.5mm Pitch, 4x1, TH	14x8.2x6.5mm
J2	1		61300411121	Würth Elektronik	Header, 2.54 mm, 4x1, Gold, TH	Header, 2.54mm, 4x1, TH
J3, J4	2		61300311121	Würth Elektronik	Header, 2.54 mm, 3x1, Gold, TH	Header, 2.54mm, 3x1, TH
J6	1		61300211121	Würth Elektronik	Header, 2.54 mm, 2x1, Gold, TH	Header, 2.54mm, 2x1, TH
L1	1	47uH	CB2518T470K	Taiyo Yuden	Inductor, Wirewound, Ferrite, 47 µH, 0.11 A, 1.235 ohm, SMD	2.5x1.8x1.8mm
R1	1	47k	CRCW060347K0JNEA	Vishay-Dale	RES, 47 k, 5%, 0.1 W, 0603	0603
R2, R3, R4	3	4.7k	CRCW06034K70JNEA	Vishay-Dale	RES, 4.7 k, 5%, 0.1 W, 0603	0603
R5, R6	2	33k	CRCW060333K0JNEA	Vishay-Dale	RES, 33 k, 5%, 0.1 W, 0603	0603
R7, R8	2	100	CRCW0603100RJNEA	Vishay-Dale	RES, 100, 5%, 0.1 W, 0603	0603
U1	1		MSP430FR2311IPW16R	Texas Instruments	16 MHz Ultra-Low-Power Microcontroller With 4 KB FRAM, 1 KB SRAM, 12 IO, 8 ch ADC10, OpAmps, TIA, PW0016A (TSSOP-16)	PW0016A
U2	1		DRV10987DPWPR	Texas Instruments	12- to 24-V, Three-Phase, Sensorless BLDC Motor Driver, PWP0024B (TSSOP-24)	PWP0024B

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Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265
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